

## N-CHANNEL ENHANCEMENT MODE VERTICAL D-MOS TRANSISTOR

N-channel enhancement mode vertical D-MOS transistor in a miniature SOT223 envelope and intended for use in relay, high-speed and line-transformer drivers.

### Features

- Direct interface to C-MOS, TTL, etc.
- High-speed switching
- No secondary breakdown

### QUICK REFERENCE DATA

Drain-source voltage	$V_{DS}$	max.	80 V
Gate-source voltage (open drain)	$\pm V_{GS0}$	max.	20 V
Drain current (DC)	$I_D$	max.	500 mA
Total power dissipation up to $T_{amb} = 25\text{ }^\circ\text{C}$	$P_{tot}$	max.	1.5 W
Drain-source ON-resistance $I_D = 500\text{ mA}; V_{GS} = 10\text{ V}$	$R_{DS\ on}$	typ.	2.0 $\Omega$
		max.	3.0 $\Omega$
Transfer admittance $I_D = 500\text{ mA}; V_{DS} = 15\text{ V}$	$ y_{fs} $	min.	150 mS
		typ.	300 mS

### MECHANICAL DATA

Fig.1 SOT223.

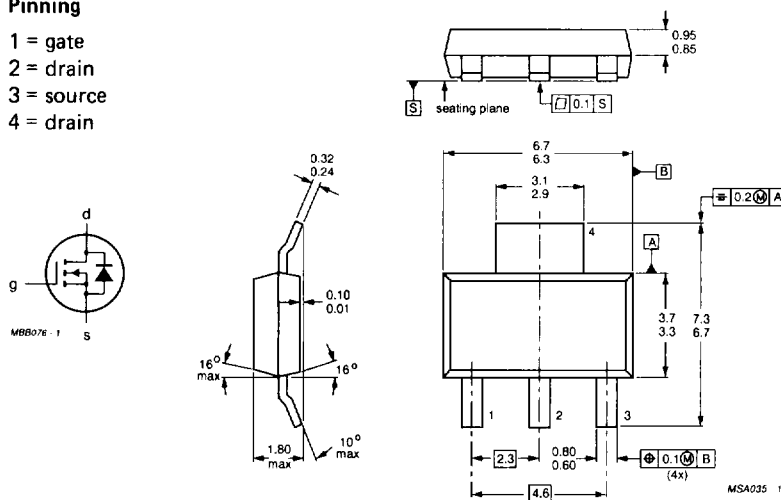
Dimensions in mm

Marking code

BSP108

### Pinning

- 1 = gate  
2 = drain  
3 = source  
4 = drain



**RATINGS**

Limiting values in accordance with the Absolute Maximum System (IEC 134)

Drain-source voltage	$V_{DS}$	max.	80 V
Gate-source voltage (open drain)	$\pm V_{GSO}$	max.	20 V
Drain current (DC)	$I_D$	max.	500 mA
Drain current (peak)	$I_{DM}$	max.	1.0 A
Total power dissipation up to $T_{amb} = 25\text{ }^\circ\text{C}$ (note 1)	$P_{tot}$	max.	1.5 W
Storage temperature range	$T_{stg}$		-65 to + 150 $^\circ\text{C}$
Junction temperature	$T_j$	max.	150 $^\circ\text{C}$

**THERMAL RESISTANCE**

From junction to ambient (note 1)	$R_{thj-a}$	=	83.3 K/W
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**CHARACTERISTICS** $T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified

Drain-source breakdown voltage $I_D = 10\text{ }\mu\text{A}; V_{GS} = 0$	$V_{(BR)DSS}$	min.	80 V
Gate threshold voltage $I_D = 1\text{ mA}; V_{GS} = V_{DS}$	$V_{GS(th)}$	min. max.	1.5 V 3.5 V
Gate-source leakage current $\pm V_{GS} = 20\text{ V}; V_{DS} = 0$	$I_{GSS}$	max.	100 nA
Drain-source leakage current $V_{DS} = 60\text{ V}; V_{GS} = 0$	$I_{DSS}$	max.	1.0 $\mu\text{A}$
Drain-source ON-resistance $I_D = 500\text{ mA}; V_{GS} = 10\text{ V}$	$R_{DS\ on}$	typ. max.	2.0 $\Omega$ 3.0 $\Omega$
Transfer admittance $I_D = 500\text{ mA}; V_{DS} = 15\text{ V}$	$ y_{fs} $	min. typ.	150 mS 300 mS
Input capacitance at $f = 1\text{ MHz};$ $V_{DS} = 10\text{ V}; V_{GS} = 0$	$C_{iss}$	typ. max.	45 pF 60 pF
Output capacitance at $f = 1\text{ MHz};$ $V_{DS} = 10\text{ V}; V_{GS} = 0$	$C_{oss}$	typ. max.	30 pF 45 pF
Feedback capacitance at $f = 1\text{ MHz};$ $V_{DS} = 10\text{ V}; V_{GS} = 0$	$C_{rss}$	typ. max.	8 pF 12 pF
Switching times (see Figs 2 and 3) $I_D = 500\text{ mA}; V_{DD} = 50\text{ V}$ $V_{GS} = 0\text{ to }10\text{ V}$	$t_{on}$	typ. max.	4 ns 8 ns
	$t_{off}$	typ. max.	10 ns 15 ns

**Note**

1. Device mounted on an epoxy printed-circuit board 40 mm x 40 mm x 1.5 mm; mounting pad for the collector lead min. 6 cm<sup>2</sup>.

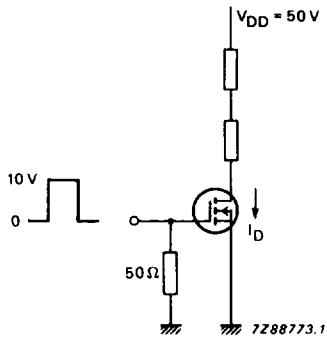


Fig.2 Switching times test circuit.

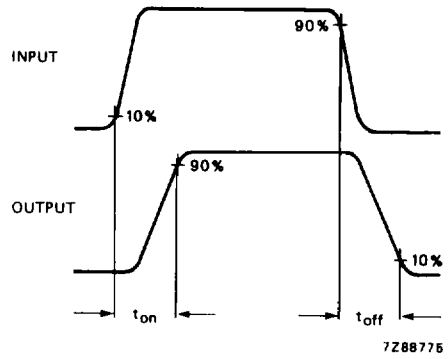


Fig.3 Input and output waveforms.

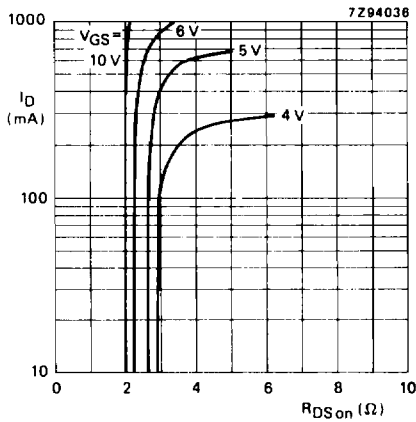


Fig.4  $T_j = 25\text{ }^\circ\text{C}$ ; typical values.

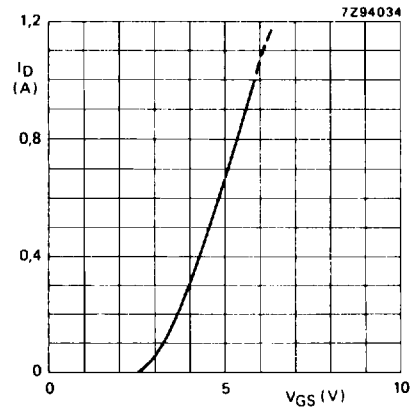


Fig.5  $T_j = 25\text{ }^\circ\text{C}$ ; typical values at  $V_{DS} = 10\text{ V}$ .

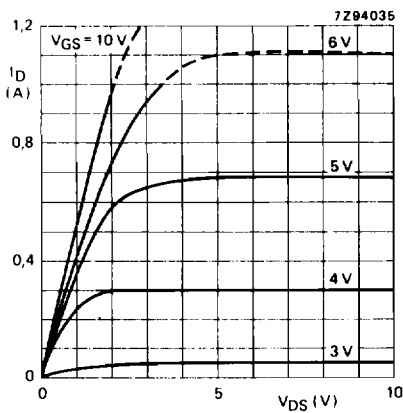


Fig.6  $T_j = 25\text{ }^\circ\text{C}$ ; typical values.

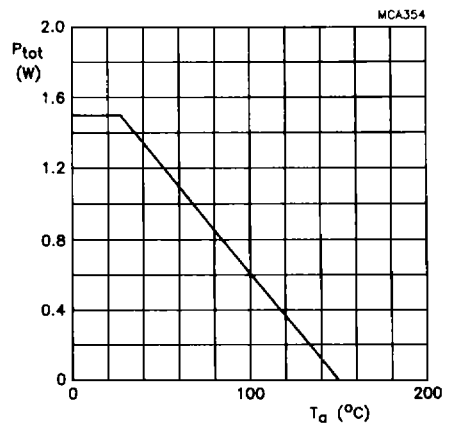


Fig.7 Power derating curve.

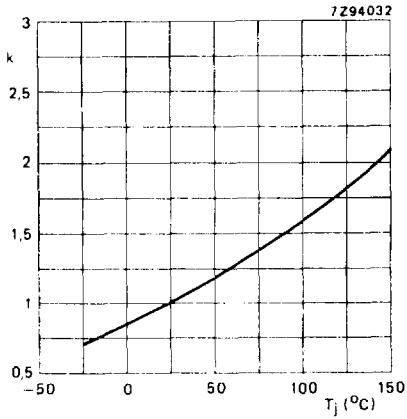


Fig.8  $k = \frac{R_{DS\ on\ at\ T_j}}{R_{DS\ on\ at\ 25\ ^\circ C}}$ ; typ. values at 500 mA/10 V.

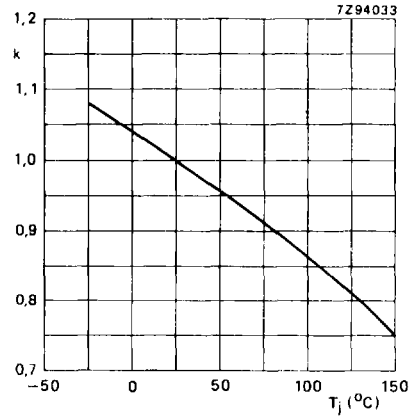


Fig.9  $k = \frac{V_{GS(th)\ at\ T_j}}{V_{GS(th)\ at\ 25\ ^\circ C}}$ ;  $V_{GS(th)}$  at 1 mA; typical values.

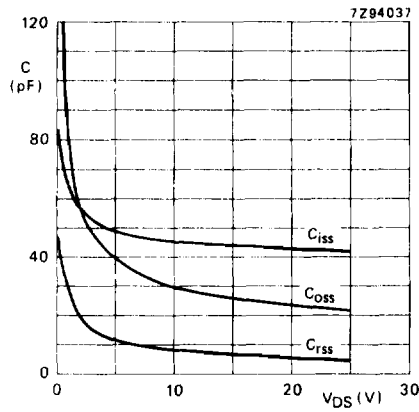


Fig.10  $T_j = 25\ ^\circ C$ ;  $V_{GS} = 0$ ;  $f = 1\ MHz$ ; typical values.